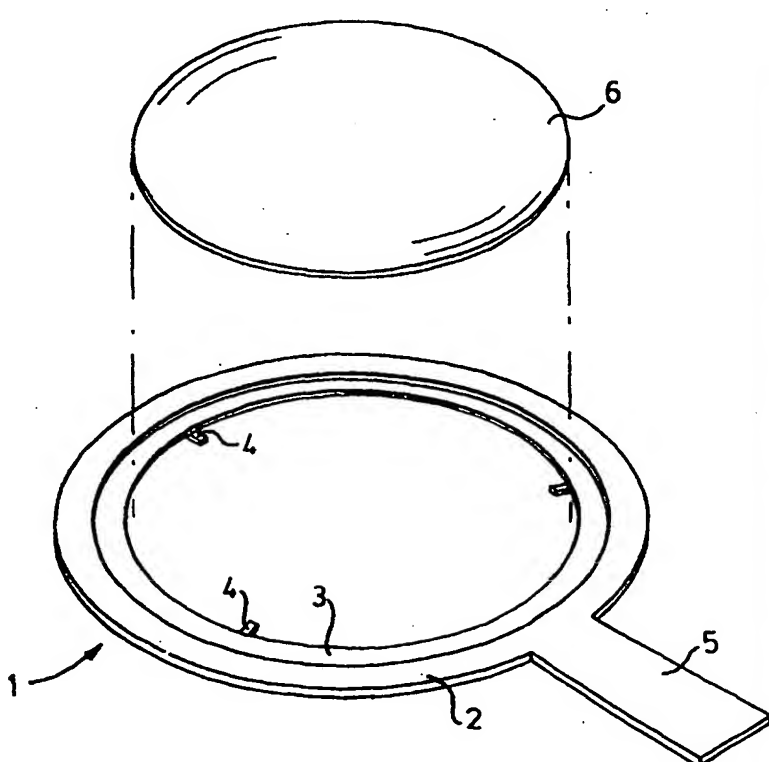


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<b>(21) International Application Number:</b> PCT/NL00/00297 <b>(22) International Filing Date:</b> 8 May 2000 (08.05.00) <b>(30) Priority Data:</b> 1012004 7 May 1999 (07.05.99) NL <b>(71) Applicant (for all designated States except US):</b> ASM INTERNATIONAL N.V. [NL/NL]; P.O. Box 100, NL-3720 AC Bilthoven (NL). <b>(72) Inventors; and</b> <b>(75) Inventors/Applicants (for US only):</b> KUZNETSOV, Vladimir Ivanovich [RU/NL]; Buenos Airesstraat 8, NL-2622 AX Delft (NL). OOSTERLAKEN, Theodorus, Gerardus, Maria [NL/NL]; Meent 4, NL-3421 GT Oudewater (NL). RIDDER, Christianus, Gerardus, Maria [NL/NL]; Esdoornlaan 19, NL-3828 BK Hoogland (NL). GRANNEMAN, Ernst, Hendrik, August [NL/NL]; Hoge Naardeweg 71 A, NL-1217 AD Hilversum (NL). <b>(74) Agent:</b> JORRITSMA, Ruurd; Nederlandsch Octrooibureau, Scheveningeweg 82, P.O. Box 29720, NL-2502 LS The Hague (NL).		<b>(81) Designated States:</b> AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CR, CU, CZ, DE, DK, DM, DZ, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, TZ, UA, UG, US, UZ, VN, YU, ZA, ZW, ARIPO patent (GH, GM, KE, LS, MW, SD, SL, SZ, TZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG).  <b>Published</b> <i>With international search report.</i>
<b>(54) Title:</b> METHOD FOR TRANSFERRING WAFERS AND RING <b>(57) Abstract</b> <p>A method and installation are proposed with which a wafer is surrounded by a ring in a floating wafer reactor. This ring is used to restrict the change in temperature over the wafer, especially during introduction and removal. Moreover, such a ring can be used to position the wafer in the horizontal plane during the treatment. The wafer is not in contact with the ring during the treatment. The ring can optionally be provided with heating means.</p> 		

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